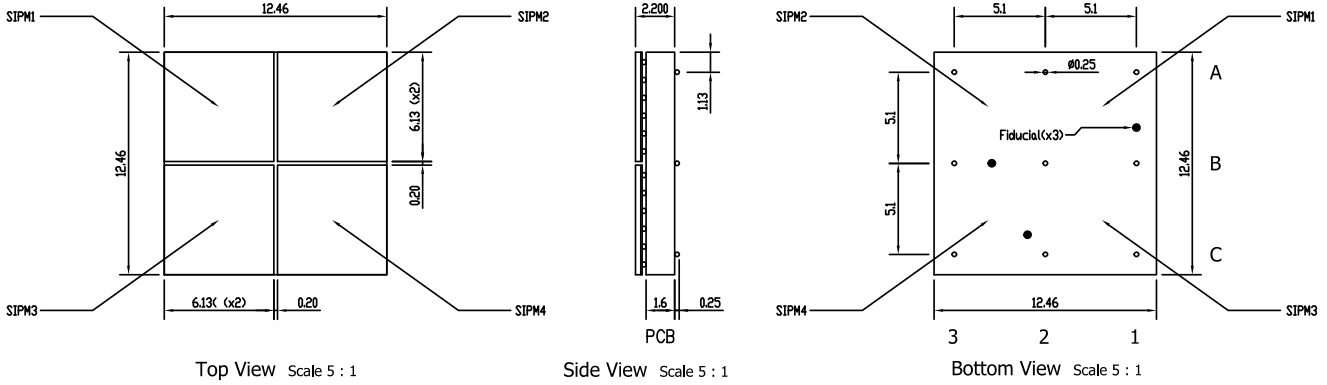


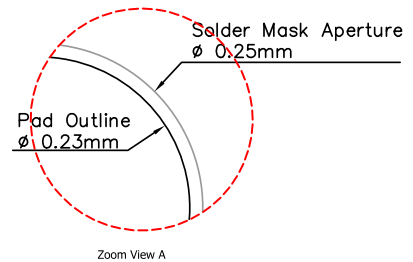
ARRAYJ-600XX-4P
CASE 100DL
ISSUE O

DATE 31 JUL 2018

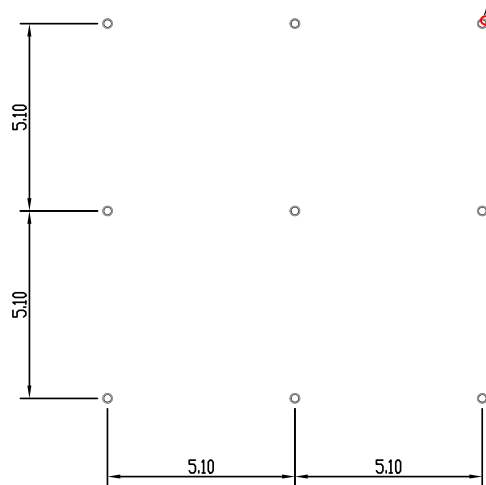


All Dimensions ± 0.1mm Unless Otherwise Stated

Solder Bump Assignments	
Bump #	Function
A1	Anode 1
A2	Anode 2
A3	Common Cathode
B1	Anode 3
B2	Anode 4
B3	Common Cathode
C1	Common Cathode
C2	Common Cathode
C3	Common Cathode



NOTE
 Solder pads may be oversized to ease placement of the array on the carrier PCB. Consult with contract manufacturer for recommendation based on placement accuracy capability.



Recommended PCB Solder Footprint
 Scale 10:1

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